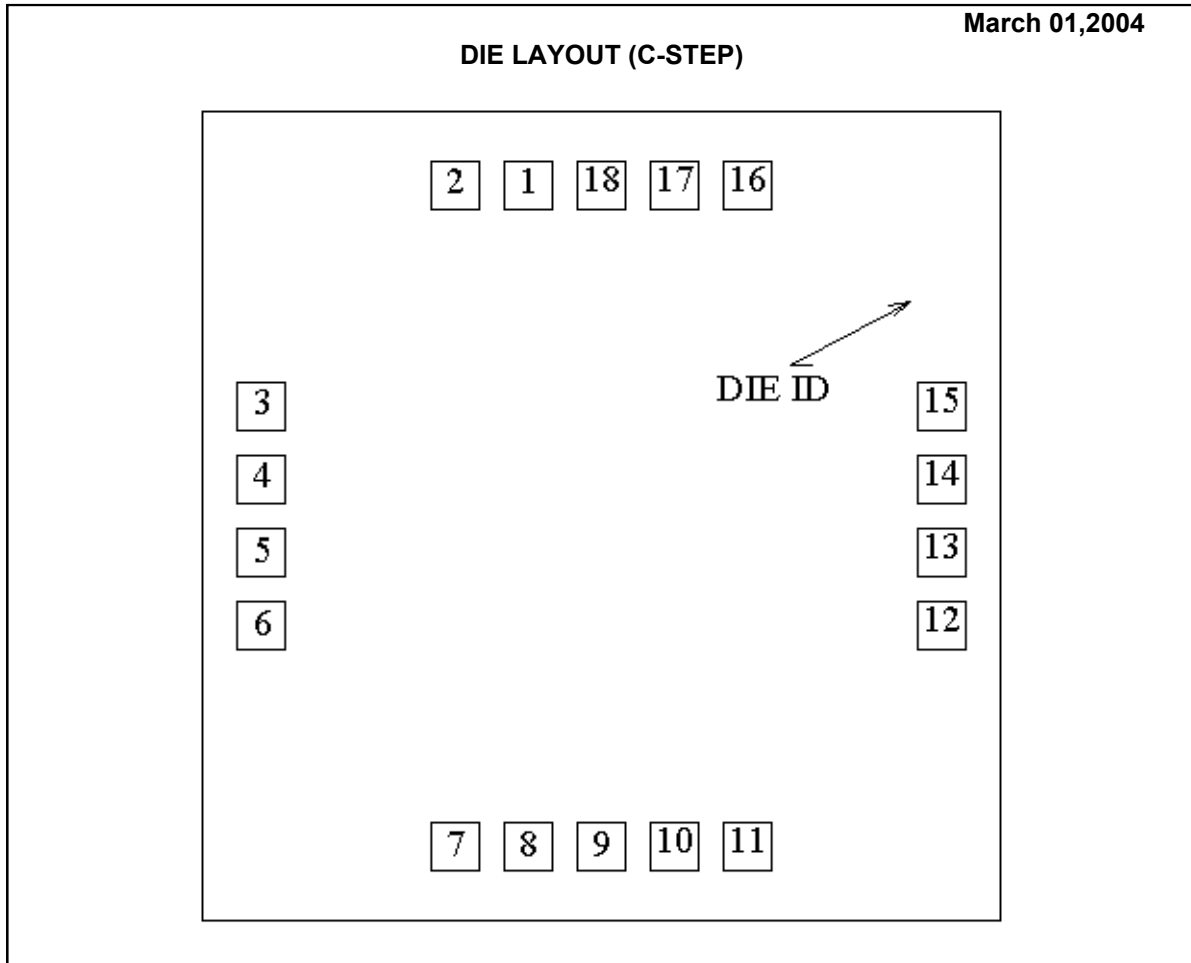


DS90C032 MD8 MW8
LVDS QUAD CMOS DIFFERENTIAL LINE RECEIVER



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	DS90C032C	Bond Pad Opening Size (min)	92µm x 92µm
Die Step	C	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	OXIDE OVER NITRIDE OVER POLYIMIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1524µm x 1549µm 60.0mils x 61.0mils	Back Side Connection	Floating
Thickness	406µm Nominal		
Min Pitch	140µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (C -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	XY COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
RIN 1-	1	-140	632	92	x	92
RIN 1+	2	-280	632	92	x	92
ROUT 1	3	-649	210	92	x	92
EN	4	-649	70	92	x	92
ROUT2	5	-649	-70	92	x	92
RIN 2+	6	-649	-210	92	x	92
RIN 2-	7	-280	-632	92	x	92
GND	8	-140	-632	92	x	92
GND	9	0	-632	92	x	92
RIN 3-	10	140	-632	92	x	92
RIN 3+	11	280	-632	92	x	92
ROUT3	12	649	-210	92	x	92
EN*	13	649	-70	92	x	92
ROUT4	14	649	70	92	x	92
RIN 4+	15	649	210	92	x	92
RIN 4-	16	280	632	92	x	92
VCC	17	140	632	92	x	92
VCC	18	0	632	92	x	92

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IN U.S.A.

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Fax: 1 207 541 6140

IN EUROPE

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Fax: 49 (0) 8141 351470

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